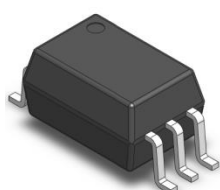
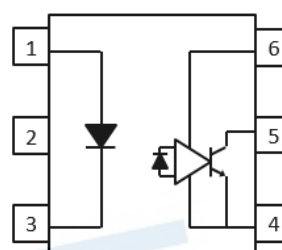


### 6 PIN SDIP HIGH SPEED 10MBit/s LOGIC GATE PHOTOCOUPLER ELS611-G series



Schematic



#### Features

- Compliance Halogen Free.  
(Br <900 ppm, Cl <900 ppm, Br+Cl < 1500 ppm).
- Pb free and RoHS compliant
- Compliance with EU REACH.
- High isolation voltage between input and output  
(Viso=5000 Vrms )
- UL and cUL approved (E214129)
- VDE approved (No.254769)
- NEMKO approved
- FIMKO approved
- SEMKO approved
- DEMKO approved
- CQC approved(No.16001145144)

0.1μF bypass capacitor must be connected between pins 6 and 4 \*3

#### Pin Configuration

- 1: Anode
- 2: No Connection
- 3: Cathode
- 4: GND
- 5: V<sub>out</sub>
- 6: V<sub>cc</sub>

#### Description

The ELS611(CLW)-G series devices are consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a storable output. The devices in a 6-pin small DIP package.

#### Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface

#### Truth Table (Positive Logic)

Input	Output
H	L
L	H

## Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	20	mA
	Reverse voltage	V <sub>R</sub>	5	V
	Power dissipation	P <sub>D</sub>	40	mW
Output	Power dissipation	P <sub>C</sub>	85	mW
	Output current	I <sub>O</sub>	50	mA
	Output voltage	V <sub>O</sub>	7.0	V
	Supply voltage	V <sub>CC</sub>	7.0	V
	Output Power Dissipation	P <sub>O</sub>	100	mW
	Isolation voltage <sup>*1</sup>	V <sub>ISO</sub>	5000	V rms
	Operating temperature	T <sub>OPR</sub>	-40 ~ +85	°C
	Storage temperature	T <sub>STG</sub>	-55 ~ +125	°C
	Soldering temperature <sup>*2</sup>	T <sub>SOL</sub>	260	°C

### Notes:

\*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3 & 4 are shorted together, and pins 5, 6, 7 & 8 are shorted together.

\*2 For 10 seconds.

## Electrical Characteristics

### Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	$V_F$	-	1.45	1.8	V	$I_F = 10\text{mA}$
Reverse Current	$I_R$	-	-	10	$\mu\text{A}$	$V_R = 5\text{V}$
Input capacitance	$C_{IN}$	-	60	-	pF	$V_F=0$ , $f=1\text{MHz}$

### Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
High Level supply current	$I_{CCH}$	-	7	13	mA	$I_F=0\text{mA}$ , $V_{CC}=5.5\text{V}$
Low Level supply current	$I_{CCL}$	-	9	15	mA	$I_F=10\text{mA}$ , $V_{CC}=5.5\text{V}$

### Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
High Level Output Current	$I_{OH}$	-	1	100	$\mu\text{A}$	$V_{CC}=5.5\text{V}$ , $V_O=5.5\text{V}$ , $I_F=250\mu\text{A}$
Low Level Output Current	$V_{OL}$	-	0.4	0.6	V	$V_{CC} = 5.5\text{V}$ , $I_F=5\text{mA}$ , $I_{OL}=13\text{mA}$
Input Threshold Current	$I_{FT}$	-	-	5	mA	$V_{CC}= 5.5\text{V}$ , $V_O=0.6\text{V}$ , $I_{OL}=13\text{mA}$

### Switching Characteristics ( $V_{CC}=5\text{V}$ , $I_F=7.5\text{mA}$ unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Propagation delay time to output High level	$T_{PHL}$	-	40	100	ns	$C_L = 15\text{pF}$ , $R_L=350\Omega$ ,
Propagation delay time to output Low level	$T_{PLH}$	-	50	100	ns	$C_L = 15\text{pF}$ , $R_L=350\Omega$ ,
Pulse width distortion	$ T_{PHL} - T_{PLH} $	-	10	50	ns	$C_L = 15\text{pF}$ , $R_L=350\Omega$
Output rise time	$t_r$	-	50	-	ns	$C_L = 15\text{pF}$ , $R_L=350\Omega$
Output fall time	$t_f$	-	10	-	ns	$C_L = 15\text{pF}$ , $R_L=350\Omega$

### Switching Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Common Mode Transient Immunity at Logic High *4	CM <sub>H</sub>	5		-	KV/ $\mu$ S	I <sub>F</sub> = 0mA , V <sub>OH</sub> =2.0V, R <sub>L</sub> =350 $\Omega$ , T <sub>A</sub> =25°C V <sub>CM</sub> =1000Vp-p
Common Mode Transient Immunity at Logic Low *5	CM <sub>L</sub>	5	-	-	KV/ $\mu$ S	I <sub>F</sub> = 7.5mA , V <sub>OL</sub> =0.8V, R <sub>L</sub> =350 $\Omega$ , T <sub>A</sub> =25°C V <sub>CM</sub> =1000Vp-p

EVERLIGHT

## Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

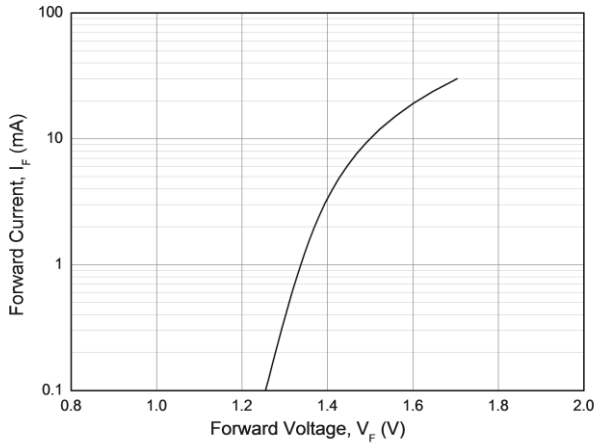


Figure 2. Low Level Output Voltage vs Ambient Temperature

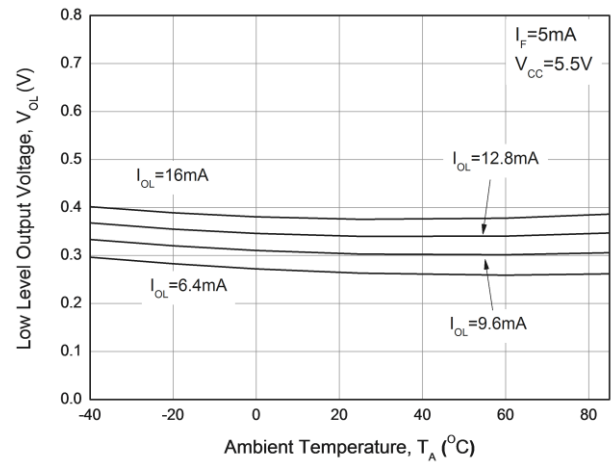


Figure 3. Low Level Output Current vs Ambient Temperature

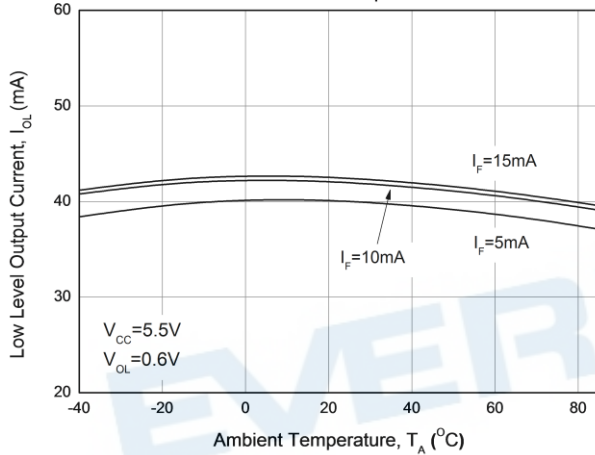


Figure 4. Input Threshold Current vs Ambient Temperature

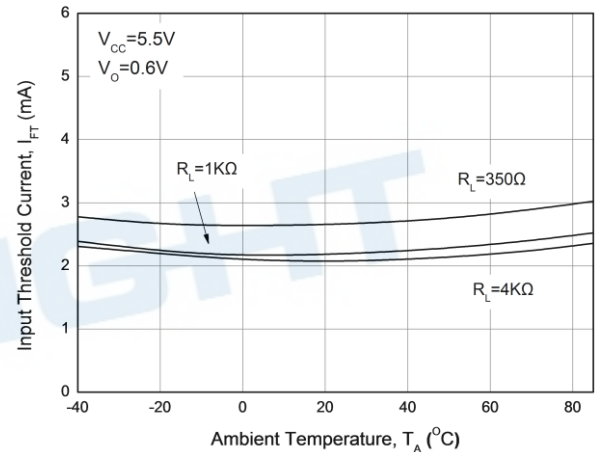


Figure 5. Input Current vs Output Voltage

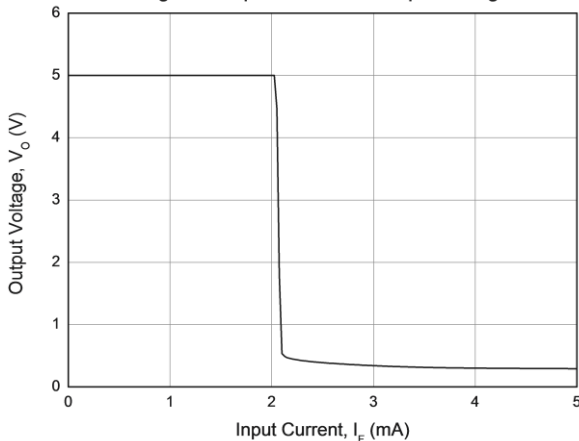


Figure 6. High Level Output Current vs Ambient Temperature

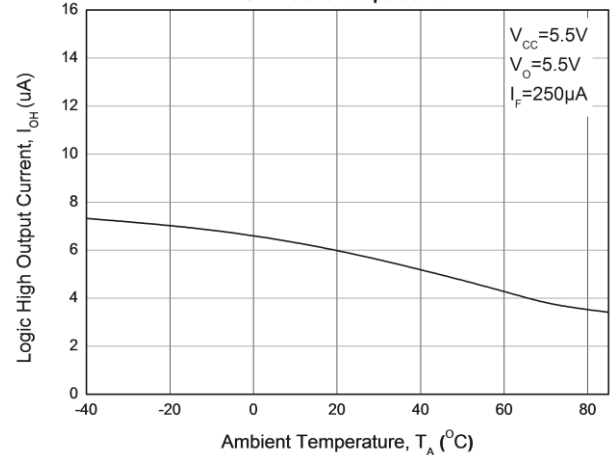


Figure 7. Propagation Delay vs. Forward Current

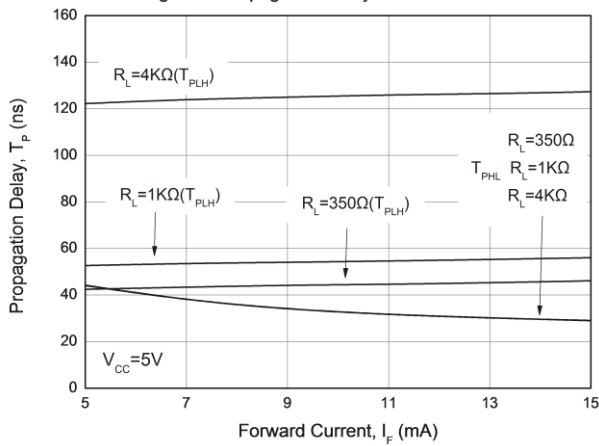


Figure 8. Propagation Delay vs. Temperature

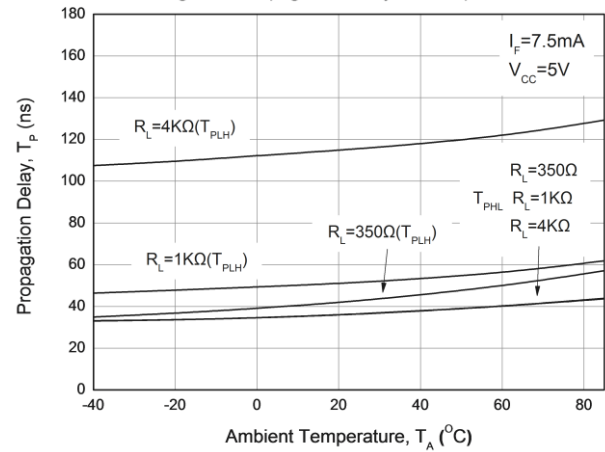


Figure 9. Pulse Width Distortion vs. Temperature

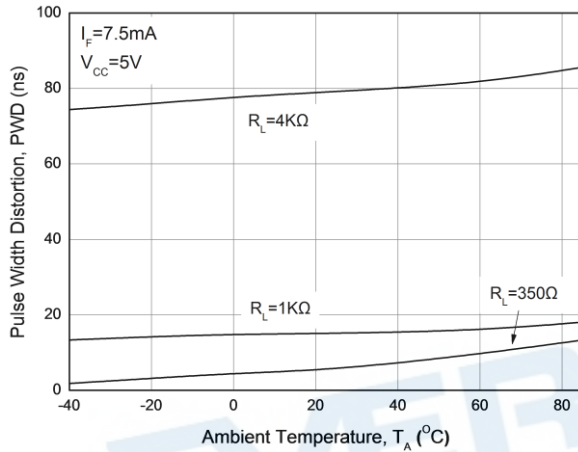
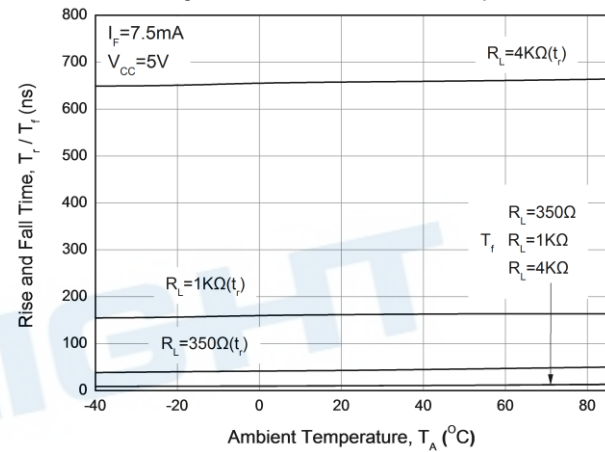


Figure 10. Rise and Fall Time vs. Temperature



The circuit diagram shows a CMOS inverter with a load resistor  $R_L$  connected to a 5V supply. The input is connected to pin 3 through a resistor, and the output is taken from pin 5. The inverter's internal structure is shown with a PMOS transistor (pin 1 to 6) and an NMOS transistor (pin 2 to 5). The input is connected to pin 3, and the output is taken from pin 5. The load resistor  $R_L$  is connected between the 5V supply and the output. The timing diagram shows the input as a square wave and the output as a square wave with a low-level voltage of -1.5V. The propagation delay times  $t_{PHL}$  and  $t_{PLH}$  are indicated.

- \*3 The  $V_{CC}$  supply must be bypassed by a  $0.1\mu F$  capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package  $V_{CC}$  and GND pins
- \*4  $CM_H$ – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e.,  $V_{OUT} > 2.0V$ ).
- \*5  $CM_L$ – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e.,  $V_{OUT} < 0.8V$ ).

## Order Information

### Part Number

**ELS611X(Y)-VG**

#### Note

EL = denotes EVERLIGHT  
S611 = part no.  
X = lead type(P)  
Y = Tape and reel option (TA, TB)  
V = VDE (optional)  
G = Halogens free

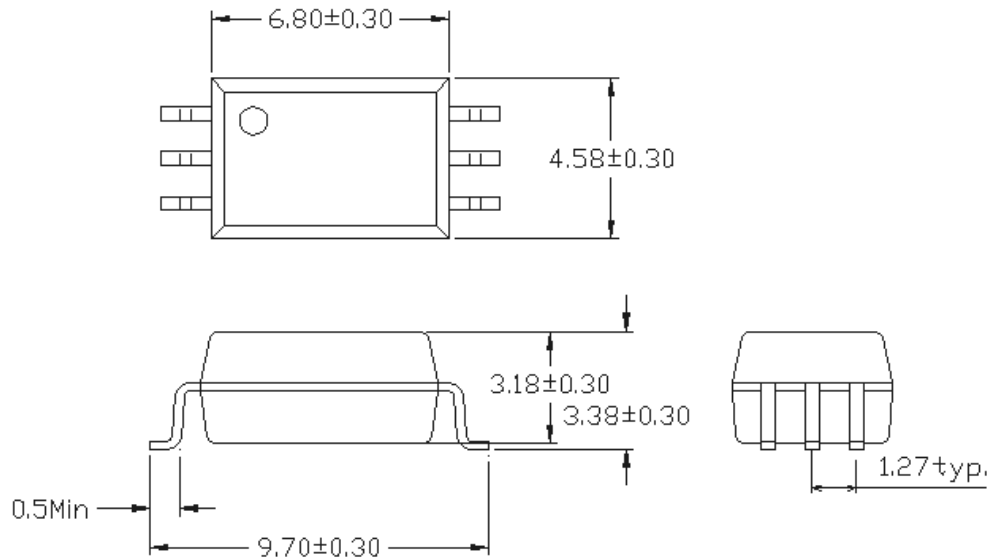
Option	Description	Packing quantity
P(TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
P(TB)	Surface mount lead form + TB tape & reel option	1000 units per reel

EVERLIGHT



**Package Dimension**  
(Dimensions in mm)

**P Type:**

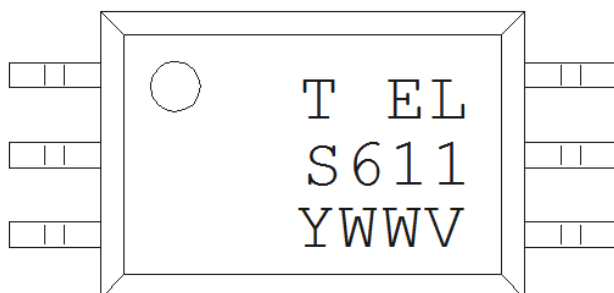


**Recommended pad layout for surface mount leadform**

**For P Type:**



## Device Marking



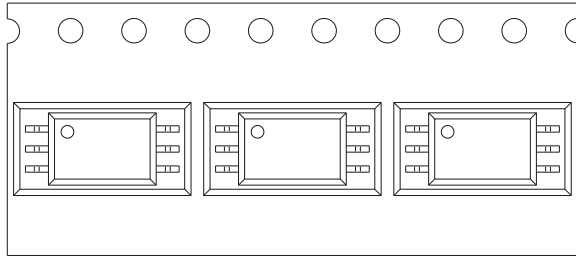
## Notes

T	denotes Factory T : made in Taiwan
EL	denotes EVERLIGHT
S611	denotes Device Number
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

EVERLIGHT

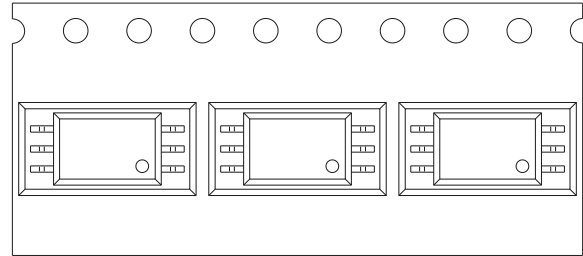
## Tape & Reel Packing Specifications

**Option TA**



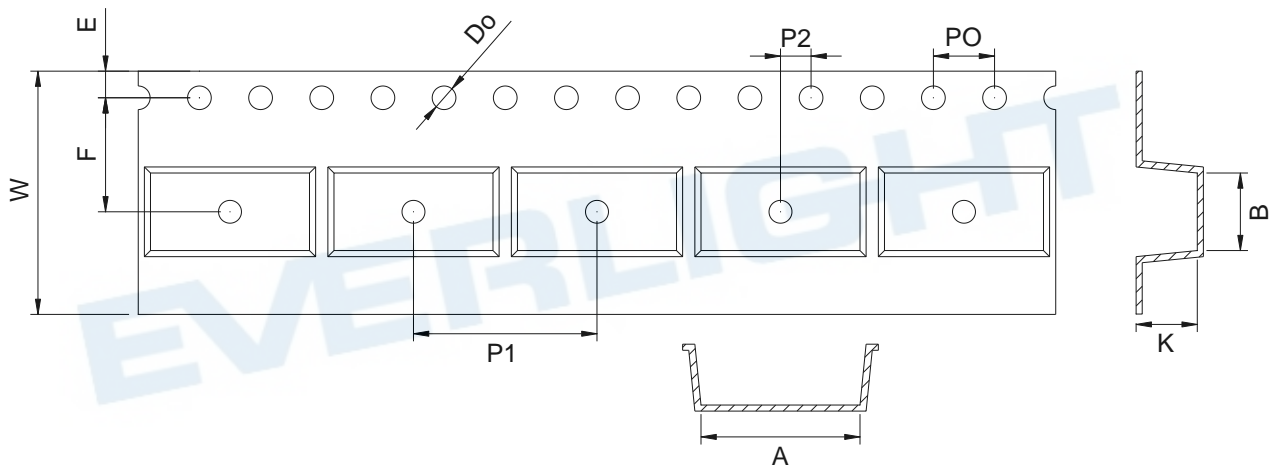
Direction of feed from reel

**Option TB**



Direction of feed from reel

## Tape dimension

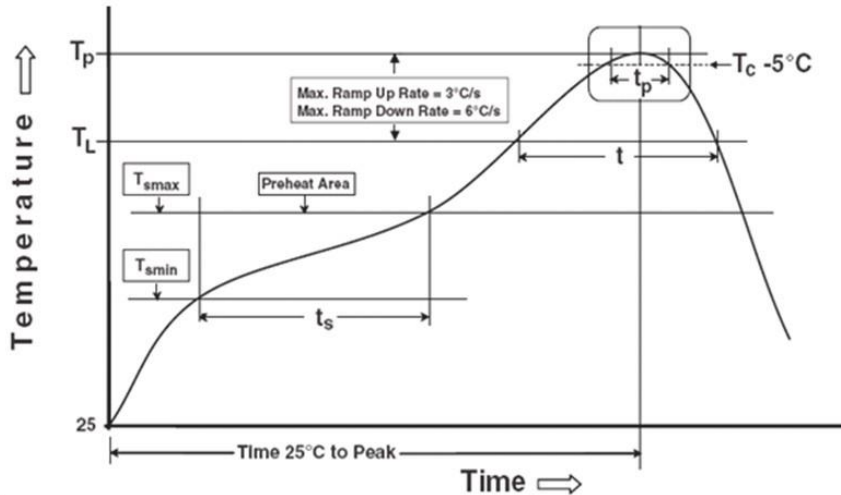


Dimension No.	A	B	Do	E	F	t
Dimension(mm) P	$10.4 \pm 0.1$	$5.1 \pm 0.1$	$1.55 \pm 0.1$	$1.75 \pm 0.1$	$7.5 \pm 0.1$	$0.4 \pm 0.1$
Dimension No.	PO	P1	P2	W	K	
Dimension(mm) P	$4.0 \pm 0.1$	$12.0 \pm 0.1$	$2.0 \pm 0.1$	$16.0 \pm 0.3$	$4.0 \pm 0.1$	

## Precautions for Use

### 1. Soldering Condition

#### 1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

#### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_P$ )	3 °C/second max

#### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100 sec
Peak Temperature ( $T_P$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_P - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

## DISCLAIMER

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
4. These specification sheets include materials protected under copyright of EVERLIGHT. Reproduction in any form is prohibited without the specific consent of EVERLIGHT.
5. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.
6. Statements regarding the suitability of products for certain types of applications are based on Everlight's knowledge of typical requirements that are often placed on Everlight products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Everlight's terms and conditions of purchase, including but not limited to the warranty expressed therein.